



# Posistrip® Products

**Organic materials specifically formulated to remove positive photoresist from substrate surfaces used in the microelectronics industry.**

Formulated to meet a wide range of process requirements, Posistrip® products vary from mildly aggressive non-alkaline chemistries for removal of photoresist from sensitive metal layers or substrates like GaAs, to very aggressive alkaline chemistries for removal of extremely hardened photoresist. These water-rinsable formulations allow the user to complete the photoresist removal process with less chemistry and lower cost of ownership (CoO). These products are low in metal ions, non-corrosive to sensitive metals and contain no phenol or chlorinated solvents. Posistrip® products are compatible with automatic equipment allowing for easy conversion from manual wet station environments.

## **Posistrip® EKC800™**

Designed to remove positive photoresist that has experienced standard processing with normal thermal history.

## **Posistrip® EKC830™**

Designed to effectively remove positive photoresist resulting from harsh prior processing that is difficult to remove.

## **Posistrip® EKC837™**

Specifically formulated for use at high temperatures. Advantages include high flash point (137°C) and the ability to remove harshly treated positive photoresist baked up to 225°C.

## **Posistrip® EKC865™**

Specifically formulated to prevent attack of sensitive metals. Removes positive photoresist with normal thermal history.

EKC offers applications engineering support for all products. This includes product development and sustaining engineering solutions. On-site consulting, process evaluation and/or additional wafer testing are available through EKC's applications engineering or R & D as needed.

**[WWW.EKCTECH.COM](http://WWW.EKCTECH.COM)**

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